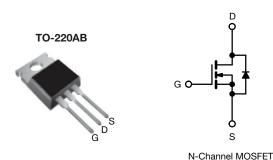
Vishay Siliconix

HALOGEN

FREE

# **EF Series Power MOSFET With Fast Body Diode**



PRODUCT SUMMARY		
$V_{DS}$ (V) at $T_J$ max.	65	50
$R_{DS(on)}$ typ. ( $\Omega$ ) at 25 °C $V_{GS} = 10 \text{ V}$ 0.		0.073
Q <sub>g</sub> max. (nC)	6	3
Q <sub>gs</sub> (nC)	Q <sub>gs</sub> (nC) 17	
Q <sub>gd</sub> (nC)	ę	)
Configuration	Sin	gle

#### **FEATURES**

- 4<sup>th</sup> generation E series technology
- Low figure of merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and halogen-free	SiHP085N60EF-T1GE3

ABSOLUTE MAXIMUM RATINGS	(T <sub>C</sub> = 25 °C, unl	ess otherwis	se noted)			
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-source voltage	V <sub>DS</sub> 600		\/			
Gate-source voltage			$V_{GS}$	± 30	30 V	
Ocalia a a dais a such (T. 450.00)	V at 10 V	$T_{\rm C} = 25  ^{\circ}{\rm C}$ $T_{\rm C} = 100  ^{\circ}{\rm C}$		34		
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C	I <sub>D</sub>	21	A	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	75		
Linear derating factor				1.82	W/°C	
Single pulse avalanche energy b						
Maximum power dissipation			$P_{D}$	184	W	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-source voltage slope $T_J = 125  ^{\circ}\text{C}$			dv/dt	100	V/ns	
Reverse diode dv/dt <sup>d</sup>				50	v/ns	

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 120 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 3.5 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ , di/dt = 100 A/ $\mu$ s, starting  $T_J$  = 25 °C



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THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R <sub>thJA</sub>	-	62	°C/W
Maximum junction-to-case (drain)	$R_{thJC}$	-	0.55	G/ <b>V</b> V

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static					•		
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.56	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3.0	-	5.0	V
Onto anima lankana		,	V <sub>GS</sub> = ± 20 V	-	-	± 100	nA
Gate-source leakage	$I_{GSS}$	,	V <sub>GS</sub> = ± 30 V	-	-	± 1	μA
7		V <sub>DS</sub> =	= 480 V, V <sub>GS</sub> = 0 V	-	-	1	μΑ
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 V	/, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	2	mA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 17 A	-	0.073	0.084	Ω
Forward transconductance a	9 <sub>fs</sub>	V <sub>DS</sub>	= 10 V, I <sub>D</sub> = 17 A	-	16	-	S
Dynamic		•					
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V,		-	2733	-	pF
Output capacitance	C <sub>oss</sub>		$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$		100	-	
Reverse transfer capacitance	C <sub>rss</sub>	f = 100 KHz		-	3	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>			-	107	-	
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>	V <sub>DS</sub> = 0 \	$V_{DS} = 0 \text{ V to } 400 \text{ V}, V_{GS} = 0 \text{ V}$		645	-	
Total gate charge	Qg			-	42	63	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$I_D = 17 \text{ A}, V_{DS} = 480 \text{ V}$	-	17	-	nC
Gate-drain charge	Q <sub>gd</sub>			-	9	-	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 480 V, I <sub>D</sub> = 17 A,		-	32	64	
Rise time	t <sub>r</sub>			-	75	113	
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		48	96	ns
Fall time	t <sub>f</sub>	7			53	80	
Gate input resistance	$R_g$	f = 1	f = 1 MHz, open drain		0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	30	
Pulsed diode forward current	I <sub>SM</sub>			-	-	75	- A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C	C, I <sub>S</sub> = 17 A, V <sub>GS</sub> = 0 V	-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>			-	109	218	ns
Reverse recovery charge	Q <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = I_S = 17 \text{ A},$ $di/dt = 100 \text{ A/µs}, V_R = 400 \text{ V}$		-	0.6	1.2	μC
Reverse recovery current	I <sub>RRM</sub>			_	11	-	A

### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 V to 400 V
- b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 V to 400 V



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

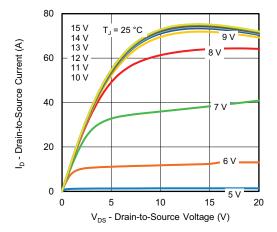


Fig. 1 - Typical Output Characteristics

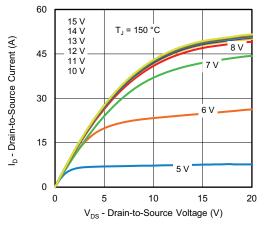


Fig. 2 - Typical Output Characteristics

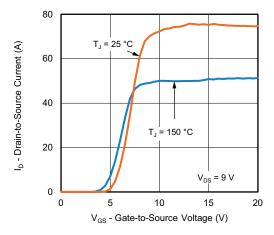


Fig. 3 - Typical Transfer Characteristics

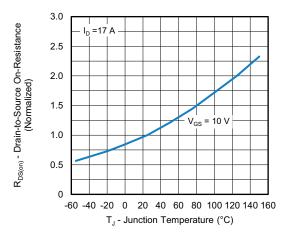


Fig. 4 - Normalized On-Resistance vs. Temperature

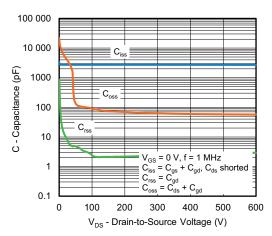


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

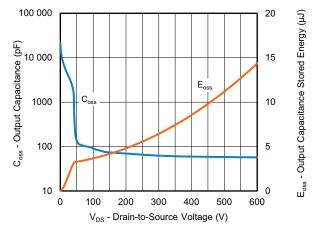


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 



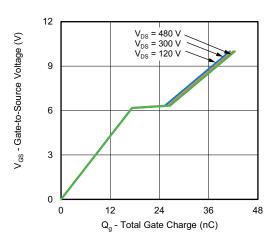


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

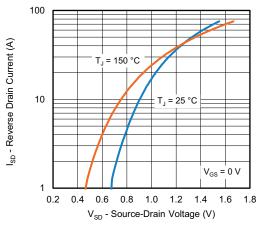


Fig. 8 - Typical Source-Drain Diode Forward Voltage

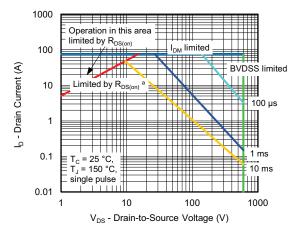


Fig. 9 - Maximum Safe Operating Area



a.  $V_{GS} > minimum \ V_{GS}$  at which  $R_{DS(on)}$  is specified

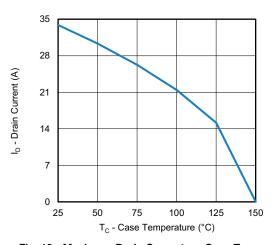


Fig. 10 - Maximum Drain Current vs. Case Temperature

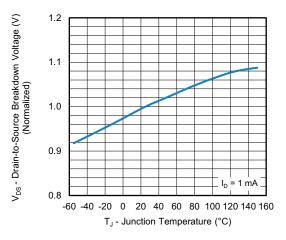


Fig. 11 - Temperature vs. Drain-to-Source Voltage



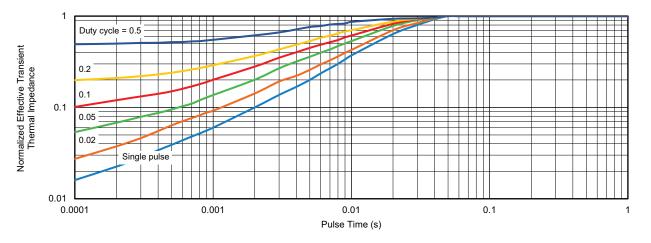


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

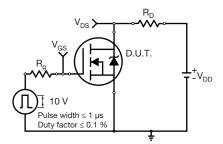


Fig. 13 - Switching Time Test Circuit

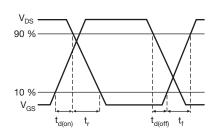


Fig. 14 - Switching Time Waveforms

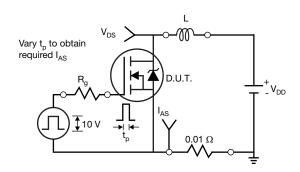


Fig. 15 - Unclamped Inductive Test Circuit

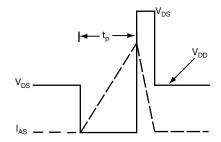


Fig. 16 - Unclamped Inductive Waveforms

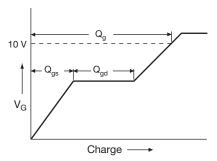


Fig. 17 - Basic Gate Charge Waveform

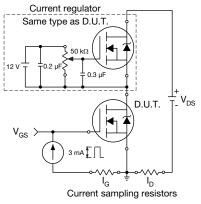
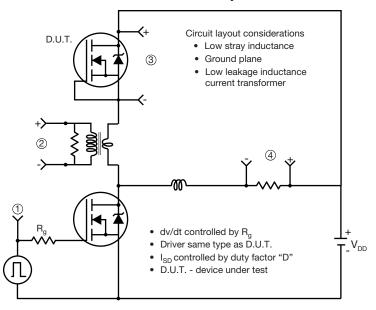


Fig. 18 - Gate Charge Test Circuit



### Peak Diode Recovery dv/dt Test Circuit



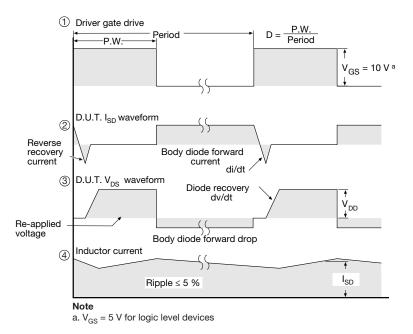
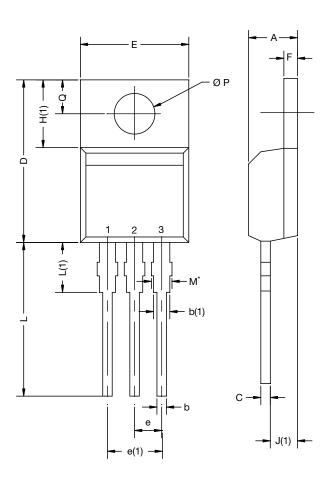


Fig. 19 - For N-Channel

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# TO-220-1



DIM.	MILLIM	METERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØP	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	

## Note

DWG: 6031

•  $M^* = 0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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